



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Jau-Shoung CHEN et al. Confirmation No: 4031  
Appl. No. : 10/693,896  
Filed : October 28, 2003  
Title : WAFER BUMPING PROCESS WITH SOLDER BALLS  
BONDED TO UNDER BUMP METALLURGY LAYER  
FORMED OVER ACTIVE SURFACE BY FORMING  
FLUX ON SOLDER BALL SURFACES  
AND REFLOWING THE SOLDER  
TC/A.U. : 2813  
Examiner : Stephen W. Smoot  
Docket No.: : CHEN3595/REF  
Customer No: : 23364

**REQUEST FOR CLARIFICATION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

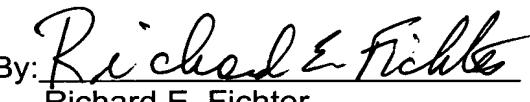
In reviewing the application prior to paying the issue fee, Applicants have advised the undersigned attorney that there is a typographical error in the title of the application as shown on PTOL 85. The title was changed to "Wafer Bumping Process With Solder Balls Bonded To Under Bump Metallurgy Layer Formed Over Active Surface By Forming Flux On Solder Ball Surfaces And Reflowing The Solder" with an Amendment filed on April 26, 2005 and has been accepted by the Examiner.

Appl. No. 10/693,896  
Request dated: July 29, 2005  
Reply to OA of: May 11, 2005

Please ensure that the correct title with the word "active" and not the word "acti" as present on the issue fee form appears on the printed patent.

Respectfully submitted,

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July 29, 2005